

Table of contents

Sheet 1: PROJECT OVERVIEW (THIS PAGE)

Sheet 2: CAN

Sheet 3: DAUGHTERBOARD

Sheet 4: MCU

Sheet 5: POWER STAGE

Sheet 6: SENSING

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.

A

Notes to generate the board layout.

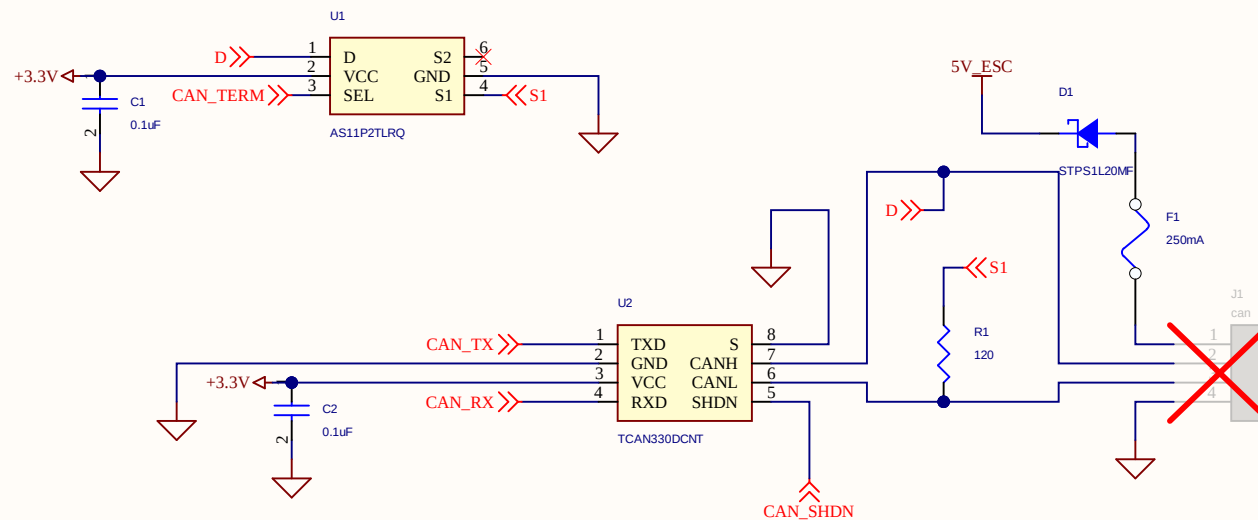
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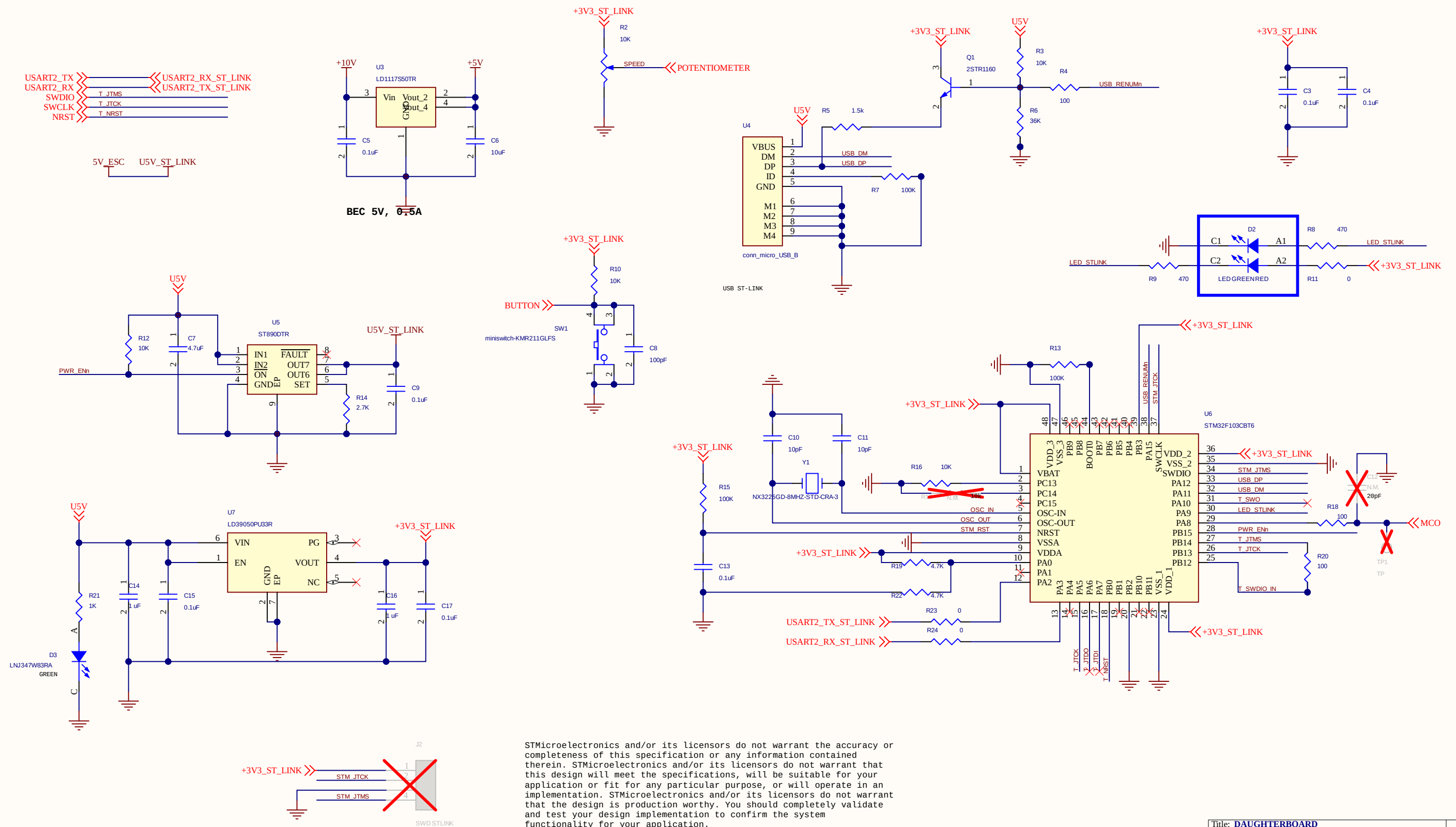
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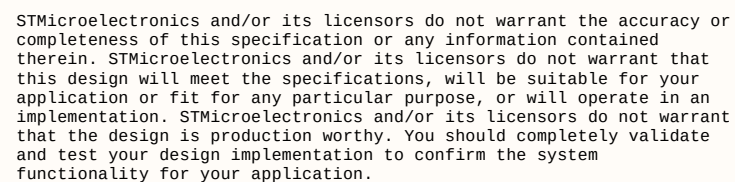
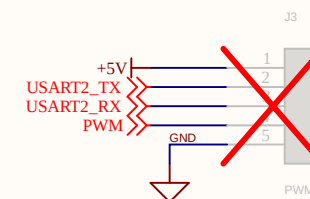
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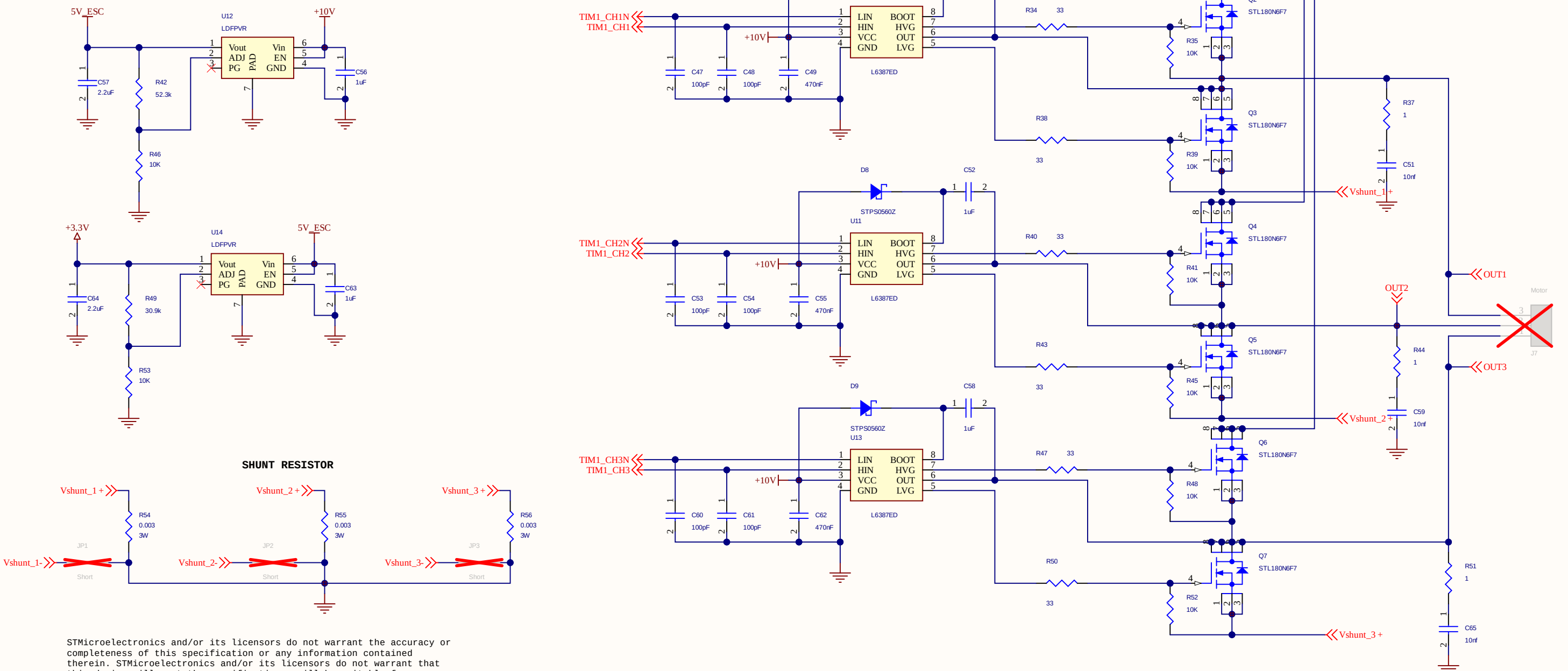
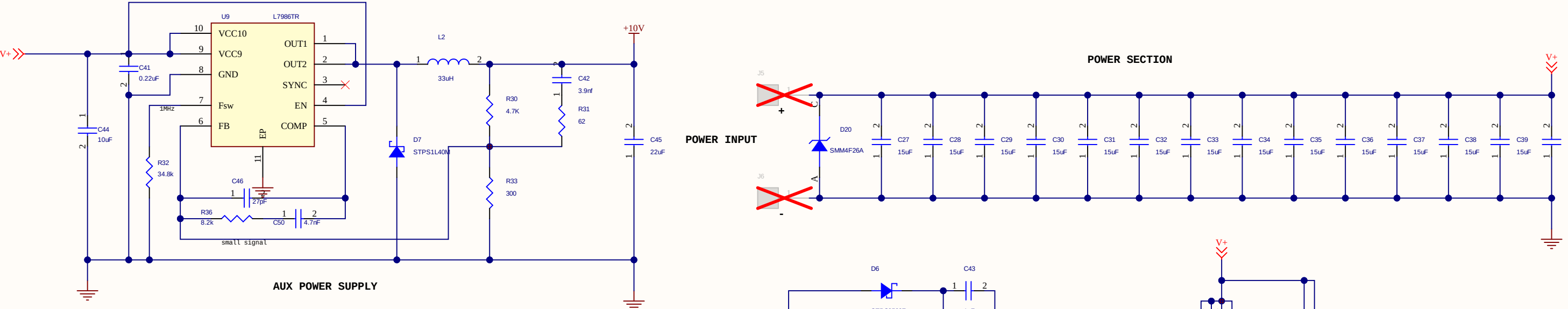




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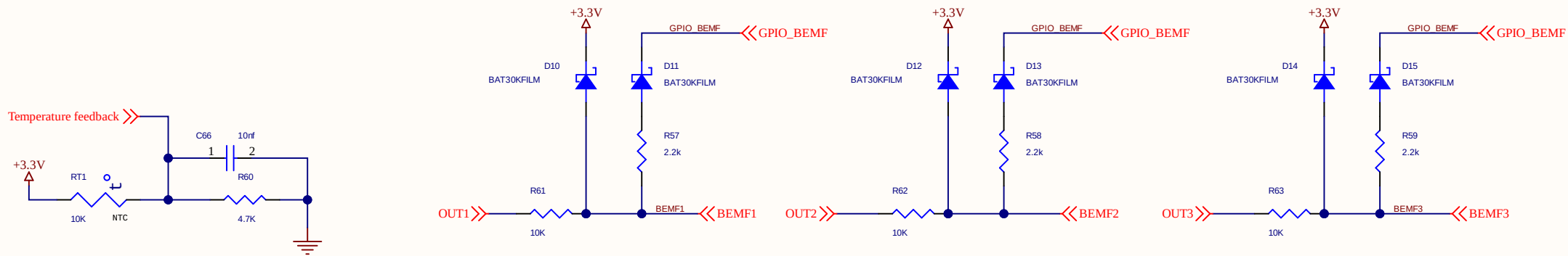




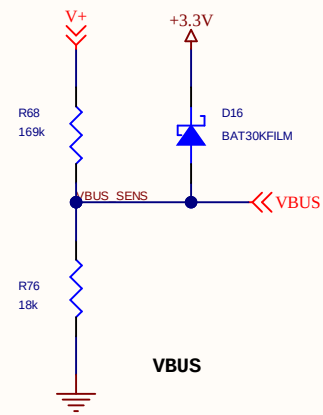
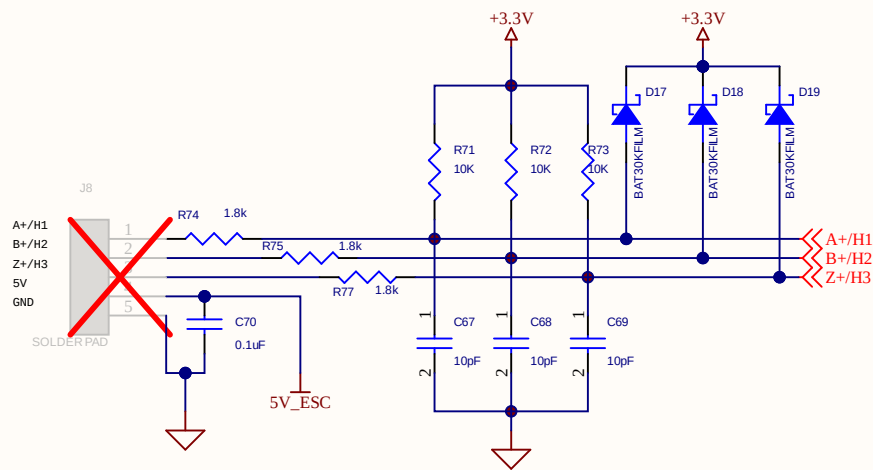


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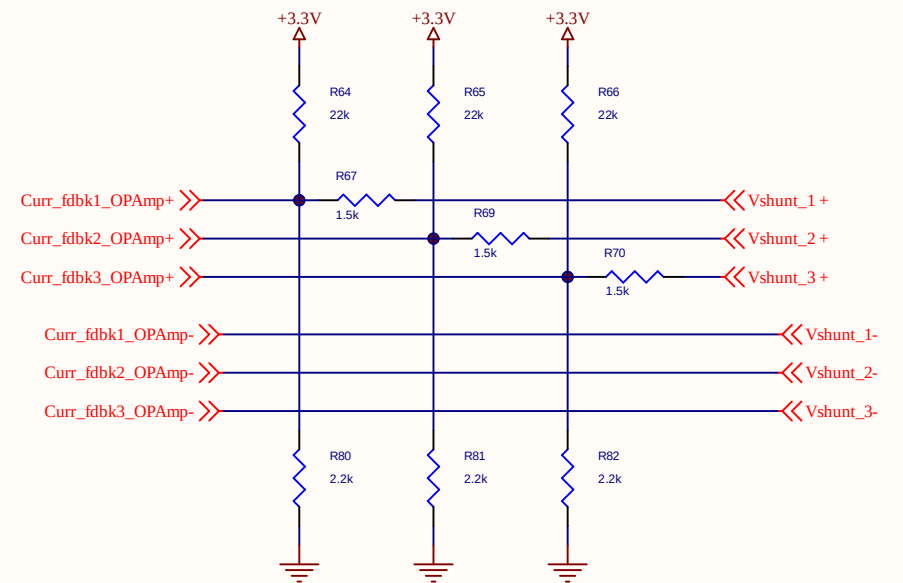
BEMF DETECTION- SIX STEP



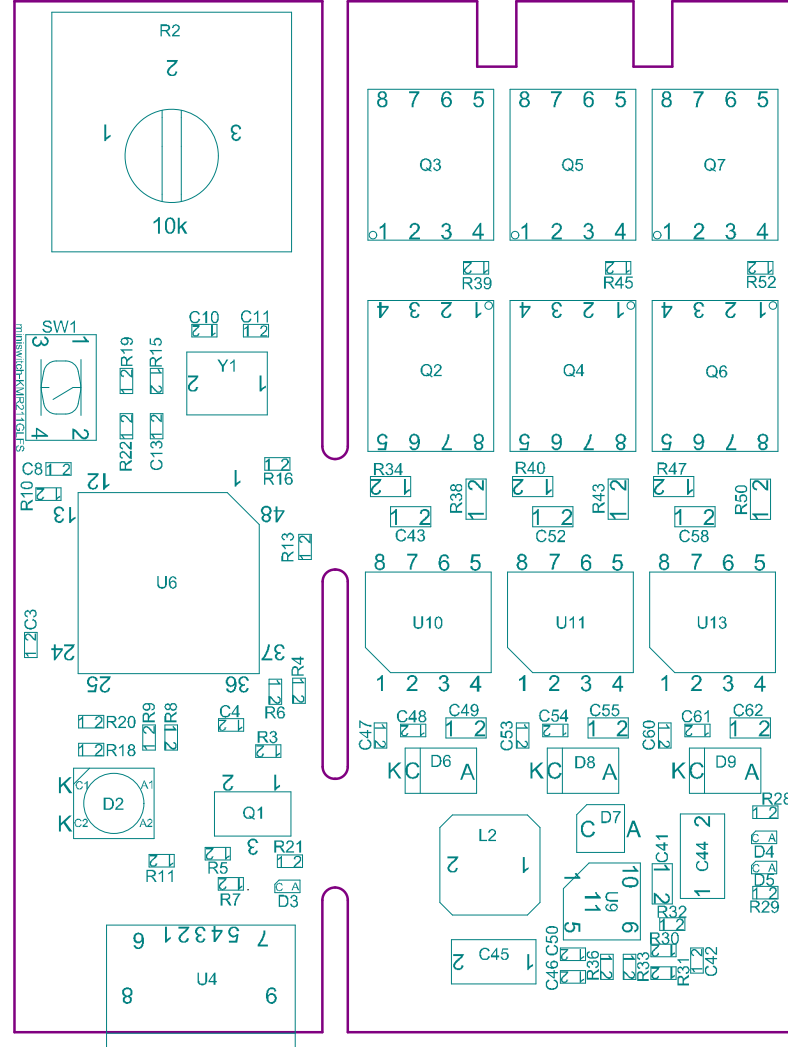
HALL/ENCODER SENSOR



SHUNT SENSING CIRCUIT

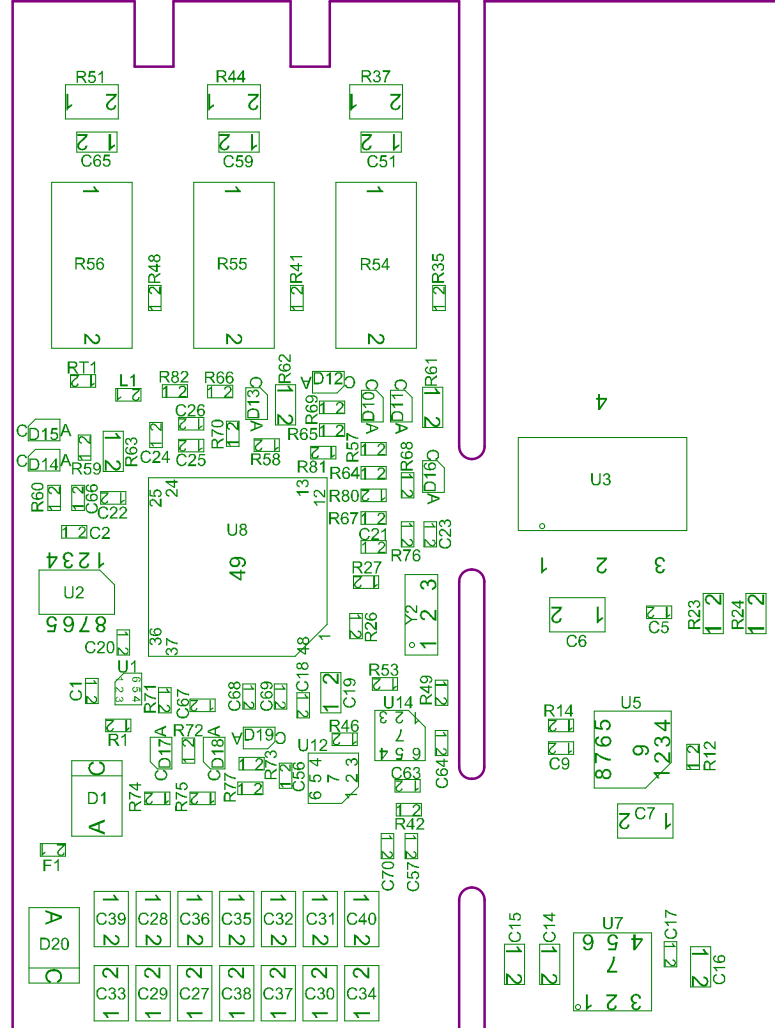


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Project: ESC_G4	
Layer: M14-Top Assembly	Gerber: .GM14
Variant: G431CBU6	Ref: MB1419
Date: 10-MAY-2020	Rev: B





Project: ESC_G4		
Layer: M15-Bottom Assembly	Gerber: .GM15	
Variant: G431CBU6	Ref: MB1419	
Date: 10-MAY-2020	Rev: B	